



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET

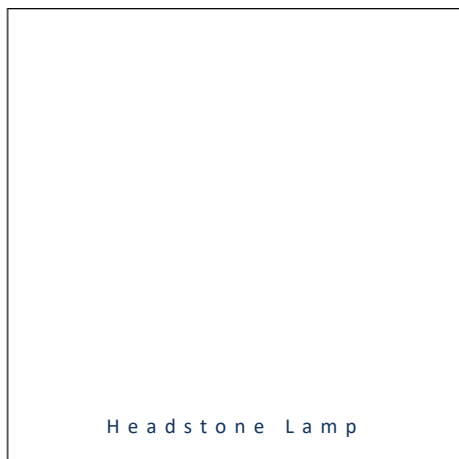


- ▶ PTH/THT Lamp
- ▶ 2.5x5.0mm Headstone  
8.6t Flangeless
- ▶ Yellow (590nm)

NOY35L75



Release Date: 03 April 2023 Version: A1.0



### Headstone Lamp

**RoHS  
Compliant**



#### FEATURES:

- **Package:** PTH/THT 2.5x5.0mm Headstone 8.6t Flangeless
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 2.0V
- **Luminous Intensity (typ.):** 25mcd@20mA
- **Colour:** Yellow
- **Dominant Wavelength (typ.):** 590nm
- **Viewing Angle:** 50°
- **Materials:**
  - Die: GaAsP on GaP
  - Resin: Epoxy (Yellow Diffused)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping Parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- **Soldering Methods:** Hand; Soldering Heat (DIP)
- **MSL Level:** acc. to JEDEC Level 3
- **Packing:** max.500pcs/bulk

#### APPLICATIONS:

- Indicator
- Signal
- 3C Application

## CHARACTERISTICS:

### Absolute Maximum Characteristics (Ta=25°C)

| Parameter                           | Symbol           | Ratings  | Unit |
|-------------------------------------|------------------|----------|------|
| Forward Current                     | I <sub>F</sub>   | 30       | mA   |
| Peak Forward Current Duty 1/10@1KHz | I <sub>FP</sub>  | 100      | mA   |
| Reverse Current @5V                 | I <sub>R</sub>   | 10       | μA   |
| Reverse Voltage                     | V <sub>R</sub>   | 5        | V    |
| Power Dissipation                   | PD               | 85       | mW   |
| Operating Temperature               | T <sub>OPR</sub> | -40~+85  | °C   |
| Storage Temperature                 | T <sub>STG</sub> | -40~+100 | °C   |

### Electrical & Optical Characteristics (Ta=25°C)

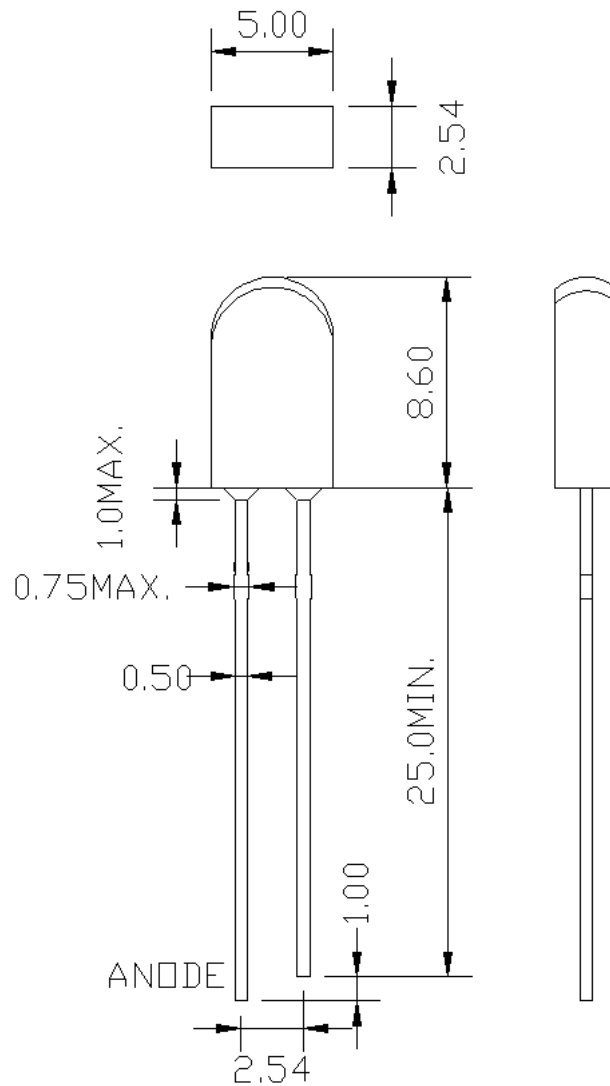
| Parameter                    | Symbol            | Values |      |      | Unit | Test Condition       |
|------------------------------|-------------------|--------|------|------|------|----------------------|
|                              |                   | Min.   | Typ. | Max. |      |                      |
| Forward Voltage              | V <sub>F</sub>    | 1.8    | 2.0  | 2.6  | V    | I <sub>F</sub> =20mA |
| Luminous Intensity           | I <sub>V</sub>    | 18     | 25   | 35   | mcd  | I <sub>F</sub> =20mA |
| Dominant Wavelength          | λ <sub>D</sub>    | 585    | 590  | 595  | nm   | I <sub>F</sub> =20mA |
| Peak Wavelength              | λ <sub>P</sub>    | ---    | 587  | ---  | nm   | I <sub>F</sub> =20mA |
| Spectral Line Half Bandwidth | Δλ                | ---    | 35   | ---  | nm   | I <sub>F</sub> =20mA |
| Viewing Angle                | 2θ <sub>1/2</sub> | ---    | 50   | ---  | deg  | I <sub>F</sub> =20mA |

1. Luminous intensity (I<sub>V</sub>) ±15%, Forward Voltage (V<sub>F</sub>) ±0.1V, Viewing angle(2θ<sub>1/2</sub>) ±5%



## OUTLINE DIMENSION:

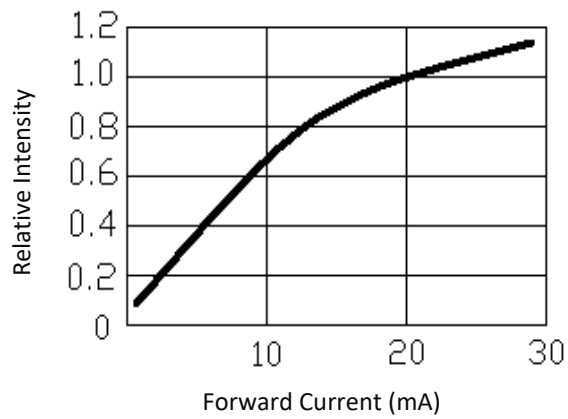
Package Dimension:



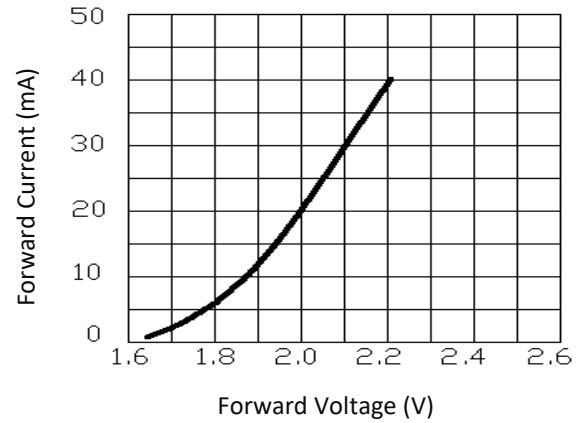
1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.2$ mm, unless otherwise noted.

## ELECTRO-OPTICAL CHARACTERISTICS:

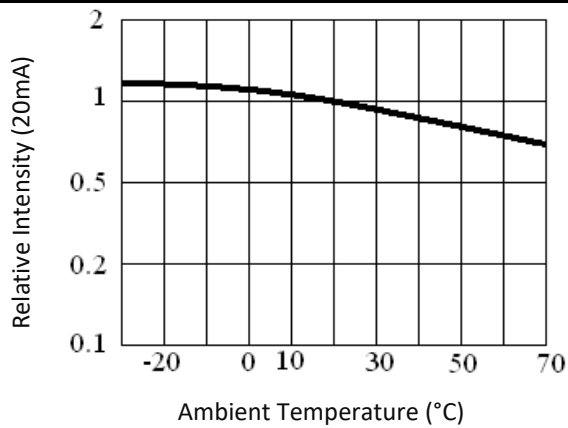
Relative Intensity v.s. Forward Current



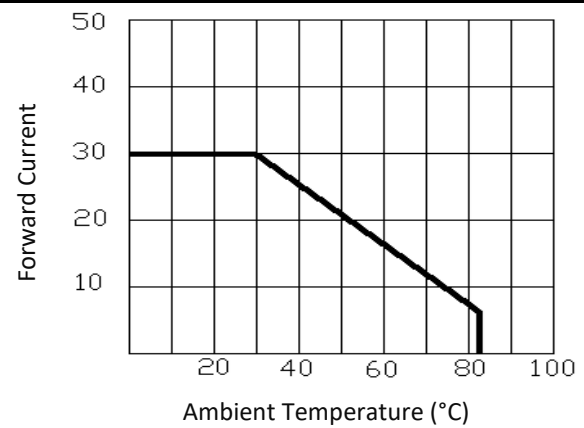
Forward Current v.s. Forward Voltage



Relative Intensity v.s. Temperature



Forward Current v.s. Temperature





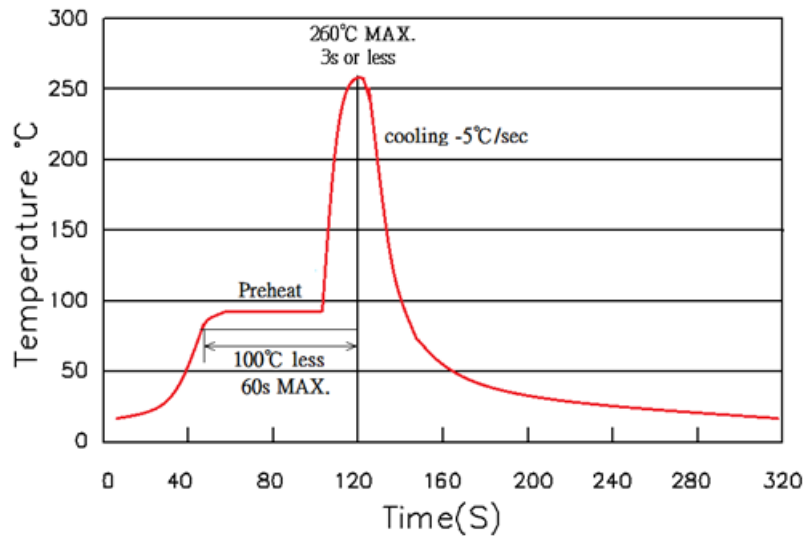
## RECOMMENDED SOLDERING PROFILE:

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### Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds  $\pm$  1 sec.

### Soldering Heat (DIP):



### Note:

1. Maximum reflow soldering: 1 time.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.

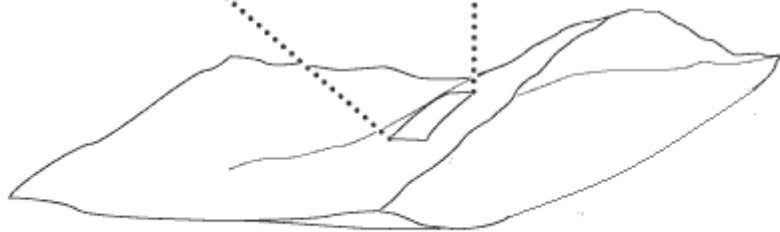


## PACKING SPECIFICATION:

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Reel Dimension:

500pcs/Bulk



## PRECAUTIONS OF USE:

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### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

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| Version | Date       | Summary of Revision |
|---------|------------|---------------------|
| A1.0    | 03/04/2023 | Datasheet set-up.   |